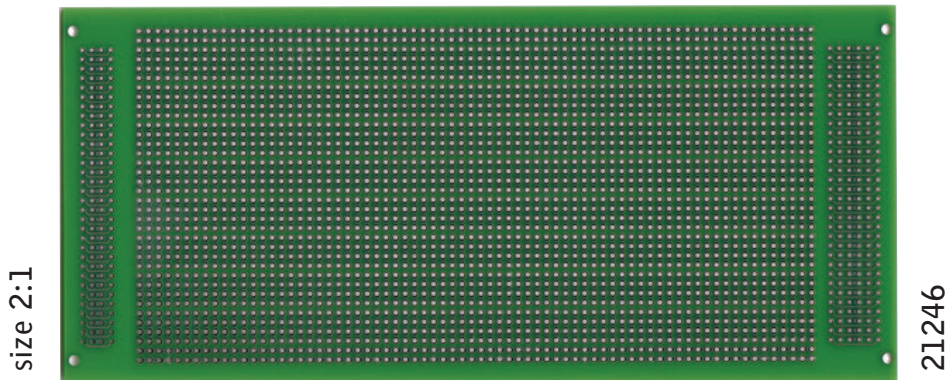


Prototyping board KU-1



- Epoxy fibre-glass FR4 thickness 1,6 mm
- Double-sided copper thickness 35 μ m
- Hot Air Solder Levelling
- Hole diameter 1,0 mm
- Size 100 x 220 mm
- Connector 32/64/96 pin DIN41612C
- Hole spacing 2,5 mm
- Plated through holes
- General hole mounted electronics